



MCP7Y60-Hxxx 400Gb/s Twin-port 2x200G OSFP to 2x200G QSFP56 DAC Splitter & 2x100GbE/EDR Product Specifications

Table of Contents

Introduction.....	3
Key Features.....	3
Applications.....	3
Overview	4
Use Cases.....	4
Pin Descriptions	5
OSFP Pin Description	5
OSFP Module Pad Layout.....	6
QSFP56 Pin Description	6
QSFP56 Module Pad Layout.....	8
Specifications.....	9
Absolute Maximum Specifications	9
Environmental Specifications	9
Operational Specifications	9
Electrical Specifications	9
OSFP Memory Map	10
QSFP56 Memory Map	12
Mechanical Specifications	13
Minimum Bend Radius.....	13
Assembly Bending Radius	13
Mechanical Drawings	14
Labels.....	16
Backshell Label.....	16
Cable Jacket Label (Middle of Cable).....	17
Regulatory Compliance and Classification	17
FCC Class A Notice	17
Cabling Information	18
Handling Precautions and Electrostatic Discharge (ESD).....	18
Cable Management Guidelines.....	18
Ordering Information.....	19
Revision History	20

Introduction

NVIDIA® MCP7Y60 is a passive Direct Attach Copper (DAC) cable with an OSFP-based twin-port 2x 200Gb/s connector to two 200Gb/s QSFP56s, and is a high-speed 200Gb/s splitter cable for InfiniBand and Ethernet networking. The DAC firmware supports both InfiniBand and Ethernet and is automatically enabled depending on the protocol of the switch attached to.

The 8-channel twin-port OSFP end uses a finned top form-factor for use in Quantum-2 and Spectrum-4 switch cages. The two 400G ends support 4-channels of 50G-PAM4 (200GbE/HDR) and use a flat top QSFP56 for use in ConnectX-6/7 adapters and BlueField-2/3 DPUs using riding heat sinks on the connector cage.

DAC cables are the lowest-cost, lowest-latency, near zero power consuming, high-speed links available due to their simplicity of design and minimal components. The “passive” term refers to the copper cable containing no electronics in the data path. Each end includes an EEPROM which provides product identification and characteristics to the host system. Every cable length is tuned to reduce internal signal noise and back reflections. Thin 30AWG is used for 1 and 1.5-meter lengths and thicker 26AWG for 2-meters.

Main use is linking Quantum-2 NDR InfiniBand and Spectrum-4 Ethernet switches to HDR/200GbE switches, ConnectX-6/7 adapters, and/or BlueField-2/3 DPUs up to 2-meters.

Switches and adapters can downshift the 4x50G-PAM4 modulation rate to 4x25G-NRZ for use in 100GbE and EDR InfiniBand switches and adapters.

NVIDIA’s cable solutions provide power-efficient connectivity enabling higher port bandwidth, density and configurability at a low cost and reduced power requirement in the data centers. Rigorous cable production testing ensures best out-of-the-box installation experience, performance, and durability.



Images are for illustration purposes only. Product labels, colors, and lengths may vary.

Key Features

- 400Gb/s to two 200Gb/s data rates
- Based on 50G-PAM4 modulation
- 1, 1.5, and 2-meter lengths
- OSFP and QSFP56 ends each consume 0.1 Watts
- Operating case temperature 0-70°C
- Single 3.3V supply voltage
- Hot pluggable
- RoHS compliant
- LSZH (Low Smoke Zero Halogen) jacket
- LF (Lead Free) HF (Halogen Free) PCB
- www.osfpmsa.org and SFF-8665 compliant
- SFF-8636 compliant I²C management interface (QSFP ends)
- CMIS compliant I²C management interface (OSFP end)

Applications

- 2x200G 2xHDR InfiniBand Quantum-2 or Spectrum-4 Ethernet switch-to-two 200Gb/s switches, QSFP56/112 ConnectX-6/7 and/or BlueField-2/3 DPUs

Overview

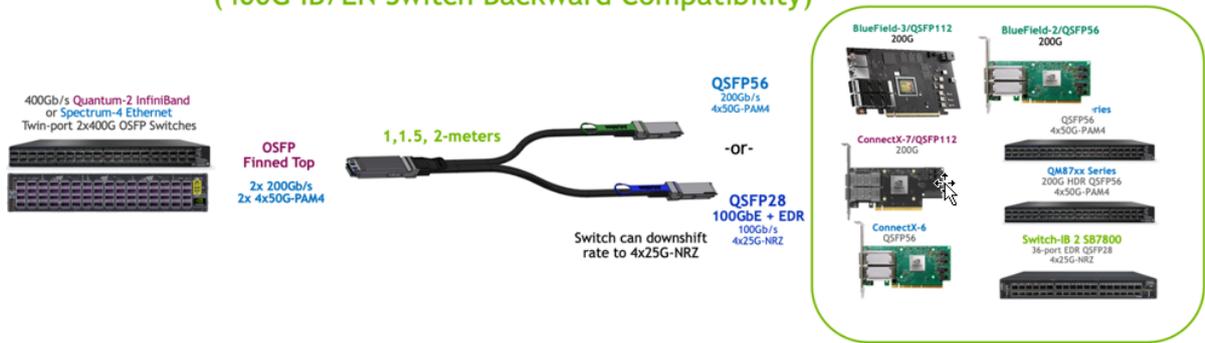
Use Cases

The MCP7Y60 is used to link Quantum-2 NDR InfiniBand and 400GbE Ethernet switches with Quantum based switches, ConnectX-6/QSFP56 adapters, and/or BlueField-2 DPUs spanning up to 2-meters.

- Both a ConnectX-6 and BlueField-2 DPU can be linked at the same time.
- 2x200G DAC can downshift the 4x50G-PM4 rate to 4x25G-NRZ supporting 100GbE and EDR InfiniBand

400G IB/EN TO 200G CONNECTIVITY MATRIX

Switch-to-Switch + Switch-to-ConnectX/BlueField DPU
(400G IB/EN Switch Backward Compatibility)



Pin Descriptions

The device is compliant with the Specification for OSFP (Octal Small Form Factor Pluggable) Modules for the head end (www.osfpmsa.org) and the SFF-8636 specification for the tails (www.snia.org/technology-communities/sff/specifications).

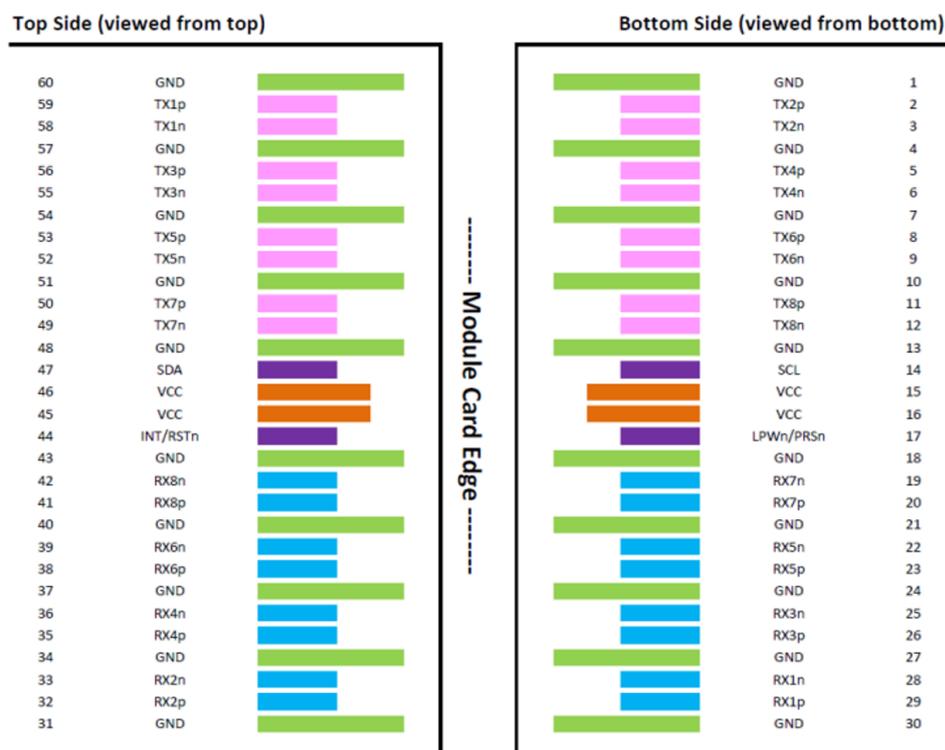
The pin assignment for the interface is shown below.

OSFP Pin Description

Pin	Symbol	Description	Pin	Symbol	Description
1	GND	Ground	31	GND	Ground
2	Tx2p	Transmitter Non-Inverted Data Input	32	Rx2p	Receiver Non-Inverted Data Output
3	Tx2n	Transmitter Inverted Data Input	33	Rx2n	Receiver Inverted Data Output
4	GND	Ground	34	GND	Grounds
5	Tx4p	Transmitter Non-Inverted Data Input	35	Rx4p	Receiver Non-Inverted Data Output
6	Tx4n	Transmitter Inverted Data Input	36	Rx4n	Receiver Inverted Data Output
7	GND	Ground	37	GND	Ground
8	Tx6p	Transmitter Non-Inverted Data Input	38	Rx6p	Receiver Non-Inverted Data Output
9	Tx6n	Transmitter Inverted Data Input	39	Rx6n	Receiver Inverted Data Output
10	GND	Ground	40	GND	Ground
11	Tx8p	Transmitter Non-Inverted Data Input	41	Rx8p	Receiver Non-Inverted Data Output
12	Tx8n	Transmitter Inverted Data Input	42	Rx8n	Receiver Inverted Data Output
13	GND	Ground	43	GND	Ground
14	SCL	2-wire serial interface clock	44	INT / RSTn	Module Interrupt / Module Reset
15	VCC	+3.3V Power	45	VCC	+3.3V Power
16	VCC	+3.3V Power	46	VCC	+3.3V Power
17	LPWn / PRSn	Low-Power Mode / Module Present	47	SDA	2-wire Serial interface data
18	GND	Ground	48	GND	Ground
19	Rx7n	Receiver Inverted Data Output	49	Tx7n	Transmitter Inverted Data Input
20	Rx7p	Receiver Non-Inverted Data Output	50	Tx7p	Transmitter Non-Inverted Data Input
21	GND	Ground	51	GND	Ground
22	Rx5n	Receiver Inverted Data Output	52	Tx5n	Transmitter Inverted Data Input

Pin	Symbol	Description	Pin	Symbol	Description
23	Rx5p	Receiver Non-Inverted Data Output	53	Tx5p	Transmitter Non-Inverted Data Input
24	GND	Ground	54	GND	Ground
25	Rx3n	Receiver Inverted Data Output	55	Tx3n	Transmitter Inverted Data Input
26	Rx3p	Receiver Non-Inverted Data Output	56	Tx3p	Transmitter Non-Inverted Data Input
27	GND	Ground	57	GND	Ground
28	Rx1n	Receiver Inverted Data Output	58	Tx1n	Transmitter Inverted Data Input
29	Rx1p	Receiver Non-Inverted Data Output	59	Tx1p	Transmitter Non-Inverted Data Input
30	GND	Ground	60	GND	Ground

OSFP Module Pad Layout

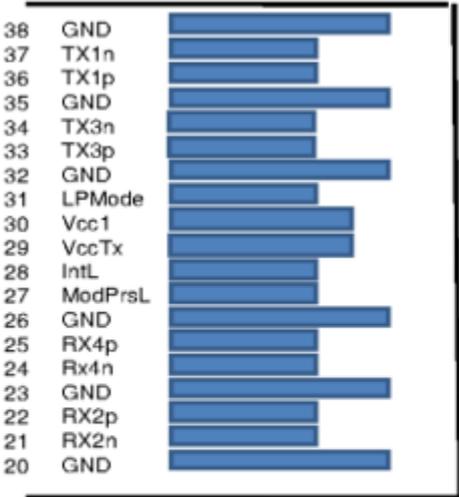


QSFP56 Pin Description

The MCP7Y60 pin assignment is SFF-8679 compliant for the two 200G 'tails' with QSFP56 form factor:

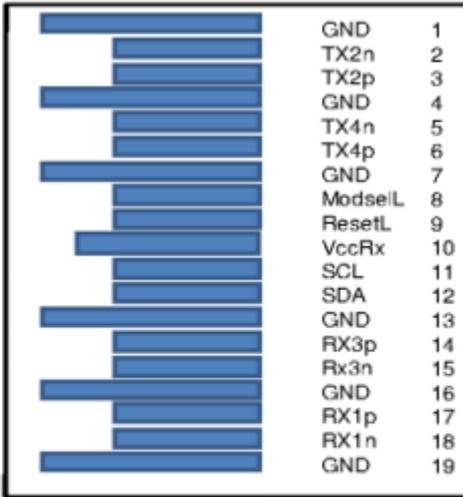
Pin	Symbol	Description	Pin	Symbol	Description
1	Ground	Ground	20	Ground	Ground
2	Tx2n	Connected to lane Rx2 Inverted Data	21	Rx2n	Connected to lane Tx2 Inverted Data
3	Tx2p	Connected to lane Rx2 Non-Inverted Data	22	Rx2p	Connected to lane Tx2 Non-Inverted Data
4	Ground	Ground	23	Ground	Grounds
5	Not connected	Not connected	24	Not connected	Not connected
6	Not connected	Not connected	25	Not connected	Not connected
7	Ground	Ground	26	Ground	Ground
8	Mod-Sell	Cable Select	27	ModPrsL	Cable Present
9	ResetL	Cable Reset	28	IntL	Interrupt
10	Vcc Rx	+3.3V Power supply receiver	29	Vcc Tx	+3.3V Power supply transmitter
11	SCL	2-wire serial interface clock	30	Vcc1	+3.3V Power Supply
12	SDA	2-wire serial interface data	31	LPMode	Low Power Mode
13	Ground	Ground	32	Ground	Ground
14	Not connected	Not connected	33	Not connected	Not connected
15	Not connected	Not connected	34	Not connected	Not connected
16	Ground	Ground	35	Ground	Ground
17	Rx1p	Connected to lane Tx1 Non-Inverted Data	36	Tx1p	Connected to lane Rx1 Non-Inverted Data
18	Rx1n	Connected to lane Tx1 Inverted Data	37	Tx1n	Connected to lane Rx1 Inverted Data
19	Ground	Ground	38	Ground	Ground

QSFP56 Module Pad Layout



Top Side Viewed From Top

Module Card Edge



Bottom Side Viewed From Bottom

Specifications

Absolute Maximum Specifications

Absolute maximum ratings are those beyond which damage to the device may occur.

Between the operational specifications and absolute maximum ratings, prolonged operation is not intended and permanent device degradation may occur.

Parameter	Min	Max	Max
Supply Voltage	-0.3	3.6	V
Data Input Voltage	-0.3	3.6	V
Control Input Voltage	-0.3	3.6	V

Environmental Specifications

This table shows the environmental specifications for the product.

Parameter	Min	Max	Units
Storage Temperature	-40	85	°C

Operational Specifications

This section shows the range of values for normal operation.

Parameter	Min	Typ	Max	Units
Supply Voltage (Vcc)	3.135	3.3	3.465	V
Power Consumption	--	--	0.1	W
Operating Case Temperature	0		70	°C
Operating Relative Humidity	5		85	%

Electrical Specifications

Parameter	Min	Typ	Max	Units	Note
Characteristic impedance	90	100	110	Ω	
Time propagation delay	--	--	4.5	ns/m	Informative

OSFP Memory Map

Page 00 Addr.	Register Name	Value and Description			
0	SFF8024 Identifier	19h: OSFP form factor 8x pluggable transceiver			
1	CMIS Revision Compliance	50h: CMIS Rev 5.0			
2	Memory Model, MciMaxSpeed	80h: Flat memory (no paging), no CLEI, max 400 kHz TWI (I2C) frequency			
3	Global status	07h: Module Ready, Interrupt not asserted			
04 - 84	Lanes and flags	00h: No lane flags, no DDM flags			
85	Media Type	03h: Passive Copper			
86 - 117		Application Descriptors (8 x 4 bytes) numbered 1...8			
Start Address	Application Descriptor	Host IF	Media IF	Host/Media Lane cnt	Host Lane Assignment
86 - 89	1	31h: InfiniBand NDR, 2 ports	01h: Copper Cable	44h: 4 host + 4 media	11h: Lane 1 and 5
90 - 93	2	2Ch: IB SDR (4x two ports)	01h	44h	11h
94 - 97	3	1Ch: Eth 800GBASE-CR8 (8x one port)	01h	44h	11h
98 - 101	4	1Bh: Eth 400GBASE-CR4 (4x two ports)	01h	22h	55h
102 - 105	5	1Ah: 200GBASE-CR2 (four ports)	01h	44h	11h
106 - 109	6	45h: 100GBASE-CR1 (eight ports)	01h	22h	55h
110 - 113	7	18h: 400GBASE-CR8 (one port)	01h	11h	FFh
114 - 117	8	16h: 200GBASE-CR4 (two ports)	01h	11h	FFh
118 - 121	Password Chg Entry				
122 - 125	Password Entry				
126	Bank Select Byte				
127	Page Select Byte				
128	SFF8024 Identifier	19h: OSFP form factor 8x pluggable transceiver (same as addr 00)			
129 - 144	VendorName	Vendor name (ASCII), padded w spaces: 'NVIDIA'			
145	VendorOUI	Nvidia OUI: 48h, B0h, 2Dh			
148 - 163	VendorPN	Part number: 'MCP7Y60-Hxxx'			
164 - 165	VendorRev	Revision			
166 - 181	VendorSN	Serial number			
182 - 189	DateCode	Date code, (YYMMDD__)			
200	Power Class	00h: Power Class 1, 07h: max power in units of 0.25 W			
201	Max power consumption	04/02 (multiplier x 0.25W)			

Page 00 Addr.	Register Name	Value and Description
202	Link Length	Cable Length (m), 7-6: multiplier x value in bits 5-0 (00 = multiplier of .1 \ 01 = multiplier of 1\10 = multiplier of 10 \11 = multiplier of 100), e.g. 41h: 1 m
203	Connector Type	Connector Type (SFF-8024) 23h: No separable connector
204 - 207	Attenuation	Cable attenuation at 5, 7, 12.9, 25.8 GHz
210	Media Lane Info	00h: all near end lanes are implemented
211	Far End Config.	03h: 2x applications with 4x lanes each (aaaa,eeee)
212	Media IF Technology	0Ah: Copper cable, unequalized
222	PageChecksum	Checksum of bytes 128-221 (low order 8 bits)
223 - 255	Custom Info	Custom data including traceability info

QSFP56 Memory Map

Page 00h	Register Name	Description
0	Identifier	11h: QSFP+ or later with SFF-8636 or SFF-8436 management interface
1	Status	08h: Support for SFF-8436 Rev. 2.8 and 2.9
113	Far End and Near End Implementations	0x10h: Both far ends and near ends has 4 lanes implemented.
128	Identifier	11h: QSFP+ or later with SFF-8636 or SFF-8436 management interface
130	Connector	23h: No separable connector (cable assembly with no separable interfaces)
139	Code for Serial Encoding Algorithm	08h: PAM4
146	Length	Length in units of 1 m: According to SFF-8636 section 6.3.12 Length: "For modules with non-separable media interfaces, this field specifies the link length of the cable assembly (copper or AOC) in units of 1 meter. Link length is as specified in the INF-8074 specification. Link lengths less than 1 meter shall indicate 1 meter."
147	Device technology	A0h: Copper cable unequalized
148-163	Vendor name	Mellanox: ASCII
164	Extended Module Codes for IB	3Fh: Supports HDR/FDR/EDR/QDR/DDR/SDR
165-167	QSFP vendor IEEE number	00-02-C9: Mellanox OUI. (different from OSFP)
168-183	Part number	Part number per backshell label (ASCII)
184-185	Product revision	ZZ: Revision per backshell label (ASCII)
186-189	Attenuation	@2.5G @5.0G @7.0G @12.9G
190	Max case temperature	46h: Support for 70°C
192	Extended specifications compliance	40h: 200GBase CR4
196-211	Serial number	MTYYWTTZZZZZ: Serial number per backshell label (ASCII).
212-217	Date code	YYMMDD: Year YY, month MM, day DD.
222	Signaling rate	6Ah: Nominal baud rate per channel, units of 250 MBd.
236	Vendor Specific	Floating part of length in units of 10cm (example: 1.5m = 0x1 in byte146 + 0x05 in byte 236)
237	Wire gauge	Wire thickness information. 1Eh: 30AWG

Mechanical Specifications

Parameter	Value		Units
Diameter	30AWG: 7.2 ±0.03 26AWG: 8.9 ±0.03		mm
Length tolerance	length < 2 m	±25	mm
	length ≥ 2 m	±50	

Minimum Bend Radius

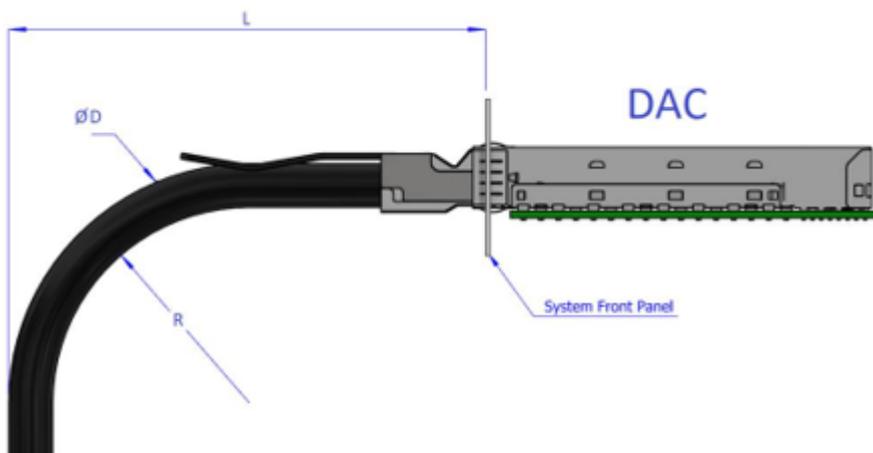
OPN	Length (m)	Cable Diameter	Min bend radius R (mm)	Assembly Space L** (mm)
MCP7Y60-H001	1.0	7.2	72	135
MCP7Y60-H01A	1.5	7.2	72	135
MCP7Y60-H002	2.0	8.9	89	156

The minimum assembly bending radius (close to the connector) is 10x the cable's outer diameter. The repeated bend (far from the connector) is also 10x the cable's outer diameter. The single bend (far from the connector) is 5x the cable's outer diameter.

**Combined end' is the 'head' where the cables join together, inserted into the switch. 'Single end' is the 'tail' which plugs into the HCA/NIC in a server.

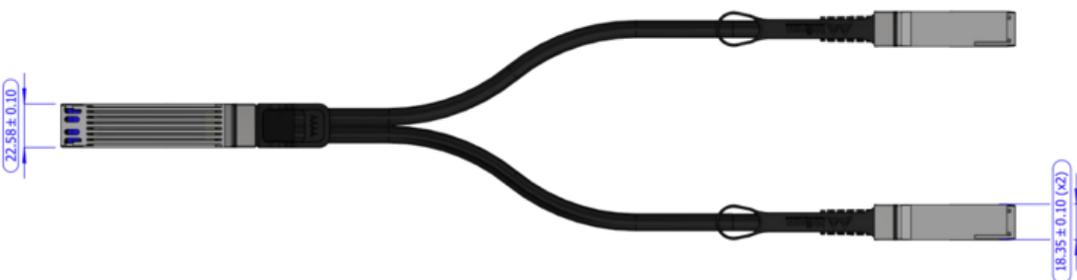
L = Assembly Space. Minimum value depends on the backshell (connector housing) dimensions = the space for the cable assembly behind the rack door.

Assembly Bending Radius



Mechanical Drawings

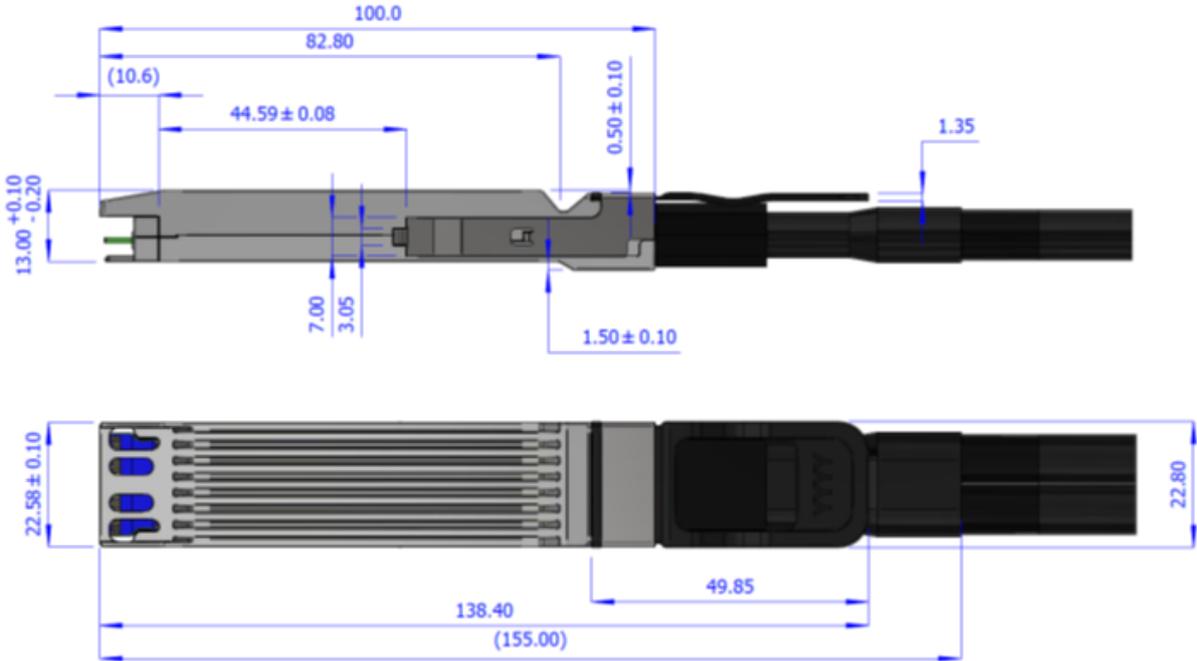
Dimensions



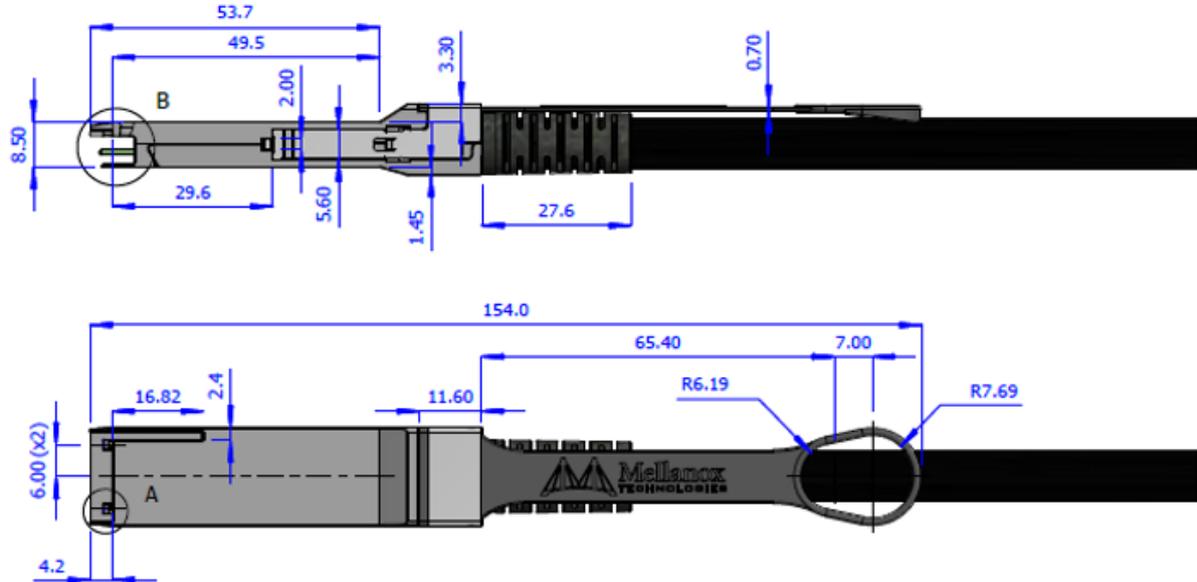
The splitting point is located at the head end, directly behind the strain relief.

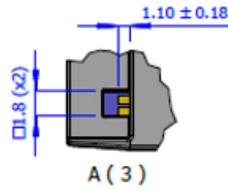
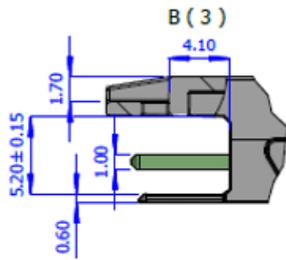


OSFP Finned Head Dimensions



QSFP Flat Ends Dimensions





UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN mm	
USE DIMENSIONS ONLY DO NOT SCALE	
GENERAL TOLERANCE:	
LINEAR:	±0.1
RADIUS:	±0.1
ANGLES:	±0.5°
BTWN HOLE CENTERS:	±0.05

Labels

Backshell Label

The following label is applied on the cable's backshell. Note that the images are for illustration purposes only. Labels look and placement may vary.

OSFP Head	QSFP56 Ends
<div style="border: 1px solid black; padding: 5px;"> <p>Model No: MCP7Y60 PN: MCP7Y60-H01A SN: MTTYWWXXSSSSS Rev: A2 1.5m 30AWG YYYY-MM-DD 400Gb/s Made In COO</p>  </div>	<div style="border: 1px solid black; padding: 5px;"> <p>Model No: MCP7Y60 PN: MCP7Y60-H01A SN: MTTYWWXXSSSSS Rev: A2 1.5m 30AWG YYYY-MM-DD 200Gb/s Made In COO</p>  </div> <p style="text-align: right;"><i>(sample illustration)</i></p>

 Images are for illustration purposes only. Product labels, colors, and form may vary.

Backshell Label Legend

Symbol	Meaning	Notes
PN - Part Number		
xx	Length	Meters
yy	Cable gauge	American wire gauge
SN - Serial Number		
MN	Manufacturer name	2 characters MT
YY	Year of manufacturing	2 digits
WW	Week of manufacturing	2 digits
MS	Manufacturer Site	2 characters
XXXXX	Serial number	5 digits for serial number. Reset at start of week to 00001.

Symbol	Meaning	Notes
Miscellaneous		
ZZ	HW and SW revision	2 alpha-numeric characters
Xm	Cable length	Meters
XXAWG	Cable gauge	American wire gauge
YYYY-MM-DD	Year-month-day	Year 4 digits, month 2 digits, day 2 digits
COO	Country of origin	E.g., China
	Quick response code	Serial number

Cable Jacket Label (Middle of Cable)

The following label is applied on the cable's jacket at each end. Note that the images are for illustration purposes only. Labels look and placement may vary.



(sample illustration)

 The serial number and barcode are for NVIDIA internal use only. Images are for illustration purposes only. Product labels, colors, and form may vary.

Regulatory Compliance and Classification

- Safety: CB, TUV, CE, EAC, UKCA
- EMC: CE, FCC, ICES, RCM, VCCI

Ask your NVIDIA FAE for a zip file of the certifications for this product.

FCC Class A Notice

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.



Cabling Information

Handling Precautions and Electrostatic Discharge (ESD)

The cable is compatible with ESD levels in typical data center operating environments and certified in accordance with the standards listed in the Regulatory Compliance Section. The product is shipped with protective caps on its connectors to protect it until the time of installation. In normal handling and operation of high-speed cables and optical transceivers, ESD is of concern during insertion into the QSFP cage of the server/switch. Hence, standard ESD handling precautions must be observed. These include use of grounded wrist/shoe straps and ESD floor wherever a cable/transceiver is extracted/inserted. Electrostatic discharges to the exterior of the host equipment chassis after installation are subject to system level ESD requirements.

Cable Management Guidelines

It is important to follow the instructions and information detailed [NVIDIA Cable Management Guidelines](#) and [FAQ Application Note](#) to insure proper and optimal installation of this cable and avoid physical damage.

Ordering Information

Ordering Part Number	Description
MCP7Y60-H001	NVIDIA passive copper splitter cable, IB twin port HDR 400Gb/s to 2x200Gb/s, OSFP to 2xQSFP56, 1m
MCP7Y60-H01A	NVIDIA passive copper splitter cable, IB twin port HDR 400Gb/s to 2x200Gb/s, OSFP to 2xQSFP56, 1.5m
MCP7Y60-H002	NVIDIA passive copper splitter cable, IB twin port HDR 400Gb/s to 2x200Gb/s, OSFP to 2xQSFP56, 2m

Revision History

Revision	Date	Description of Changes
1.2	Apr. 2023	Formatted for html on-line.
1.1	Feb. 2023	Updated the Mechanical Drawings.
1.0	Dec. 2022	Initial release. Preliminary and subject to change.

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